



# ACEDC3904B

## N-Channel Enhancement Mode Power MOSFET

### Description

ACEDC3904B uses advanced trench technology and design to provide excellent  $R_{DS(on)}$  with low gate charge. It can be used in a wide variety of applications.

### Features

- $V_{DS}=30V$  ,  $I_D=50A$
- $R_{DS(ON)}$  @  $V_{GS}=10V$ , TYP 3.5m $\Omega$
- $R_{DS(ON)}$  @  $V_{GS}=4.5V$  , TYP 5m $\Omega$

### Absolute Maximum Ratings

Parameter		Symbol	Max	Unit
Drain-Source Voltage		$V_{DSS}$	30	V
Gate-Source Voltage		$V_{GSS}$	$\pm 20$	V
Drain Current (Continuous)*AC	$T_A=25^\circ C$	$I_D$	50	A
	$T_A=100^\circ C$		35	
Drain Current (Pulsed)*B		$I_{DM}$	100	A
Power Dissipation	$T_A=25^\circ C$	$P_D$	23	W
Operating temperature / storage temperature		$T_J/T_{STG}$	-55~150	$^\circ C$

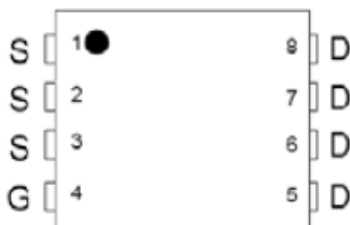
A: The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ C$ . The value in any given application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature.

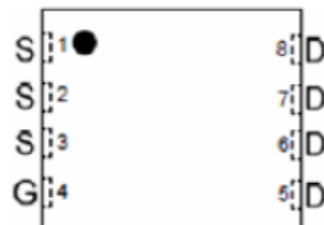
C: The current rating is based on the  $t \leq 10s$  junction to ambient thermal resistance rating.

### Packaging Type

PDFN3\*3-8L



DFN3\*3-8L



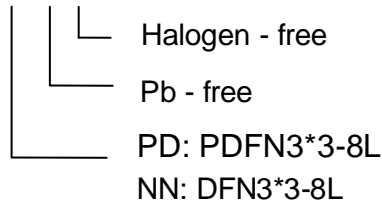


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### Ordering information

ACEDC3904B XX + H



### Electrical Characteristics

$T_A=25^{\circ}\text{C}$ , unless otherwise specified.

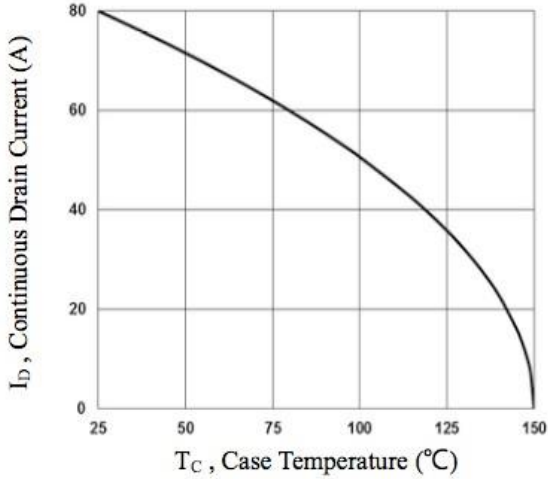
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30			V
Zero Gate Voltage Drain Current	$I_{DSS1}$	$V_{DS} = 40V, V_{GS} = 0V$			1	$\mu A$
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_{DS} = 250\mu A$	1.2	1.6	2.5	V
Gate Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 100$	nA
Drain-Source On-state Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 24A$		3.5	4.5	m $\Omega$
		$V_{GS} = 4.5V, I_D = 12A$		5	6	
Forward Trans Conductance	$g_{FS}$	$V_{DS} = 10V, I_D = 10A$		28		S
Diode Forward Voltage	$V_{SD}$	$I_{SD} = 1A, V_{GS} = 0V$			1	V
Diode Forward Current	$I_S$				80	A
Switching						
Total Gate Charge	$Q_g$	$V_{DS} = 15V, I_D = 24A, V_{GS} = 4.5V$		24		nC
Gate-Source Charge	$Q_{gs}$			4.2		nC
Gate-Drain Charge	$Q_{gd}$			13		nC
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 15V, I_D = 10A, V_{GS} = 10V, R_G = 3.3\Omega$		12.3		ns
Turn-on Rise Time	$t_r$			1.5		ns
Turn-off Delay Time	$t_{d(off)}$			42.8		ns
Turn-off Fall Time	$t_f$			13.2		ns
Dynamic						
Input Capacitance	$C_{iss}$	$V_{DS} = 25V, V_{GS} = 0V, f = 1.0MHz$		2200		pF
Output Capacitance	$C_{oss}$			280		pF
Reverse Transfer Capacitance	$C_{rss}$			177		pF



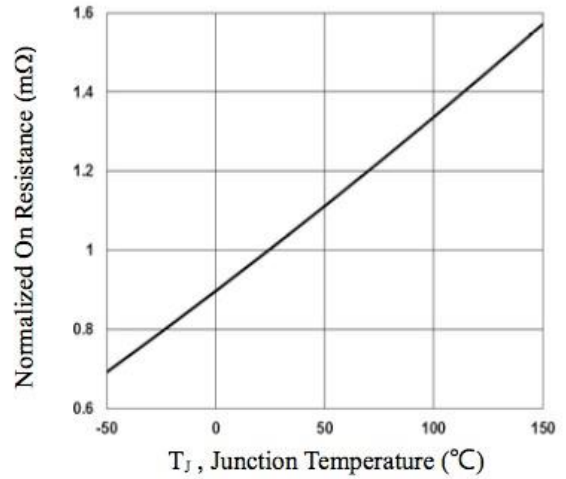
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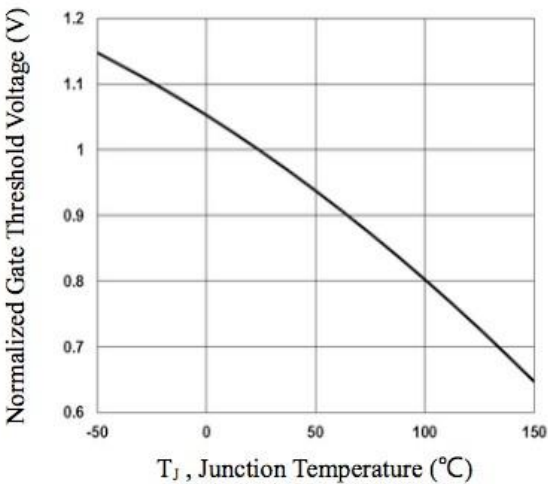
### Typical Performance Characteristics



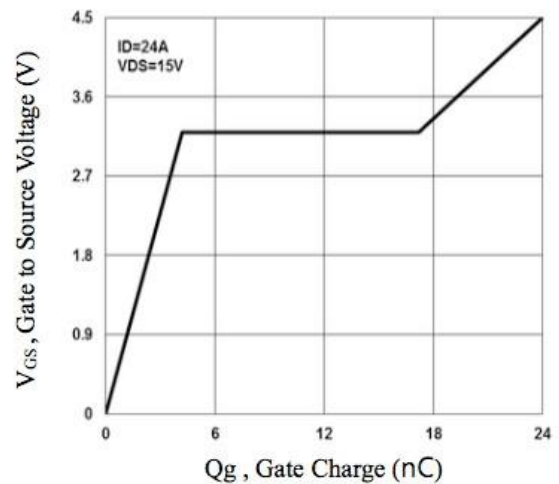
**Fig.1 Continuous Drain Current vs.  $T_C$**



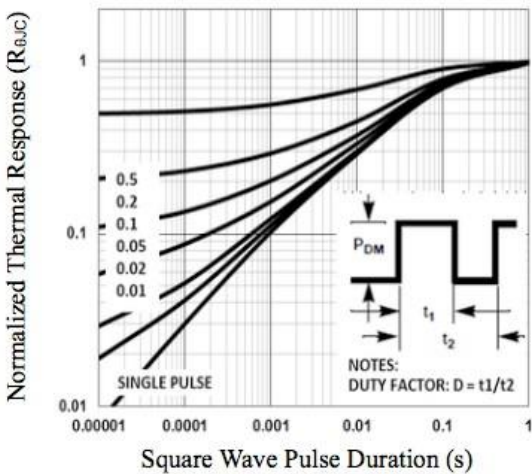
**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$**



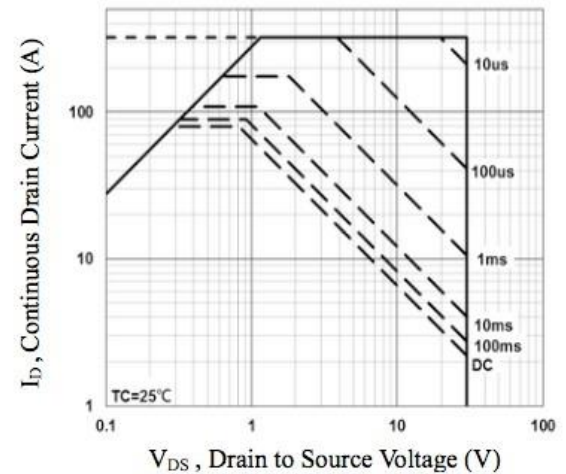
**Fig.3 Normalized  $V_{th}$  vs.  $T_J$**



**Fig.4 Gate Charge Waveform**



**Fig.5 Normalized Transient Impedance**

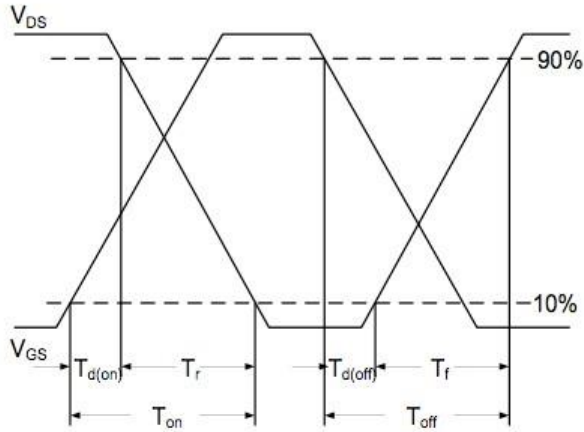


**Fig.6 Maximum Safe Operation Area**

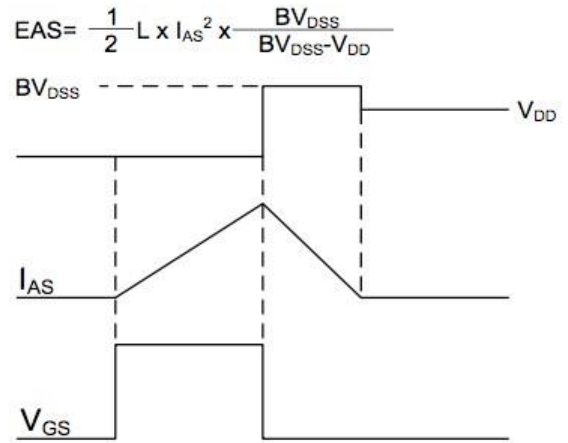


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**Fig.7 Switching Time Waveform**



$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

**Fig.8 EAS Waveform**

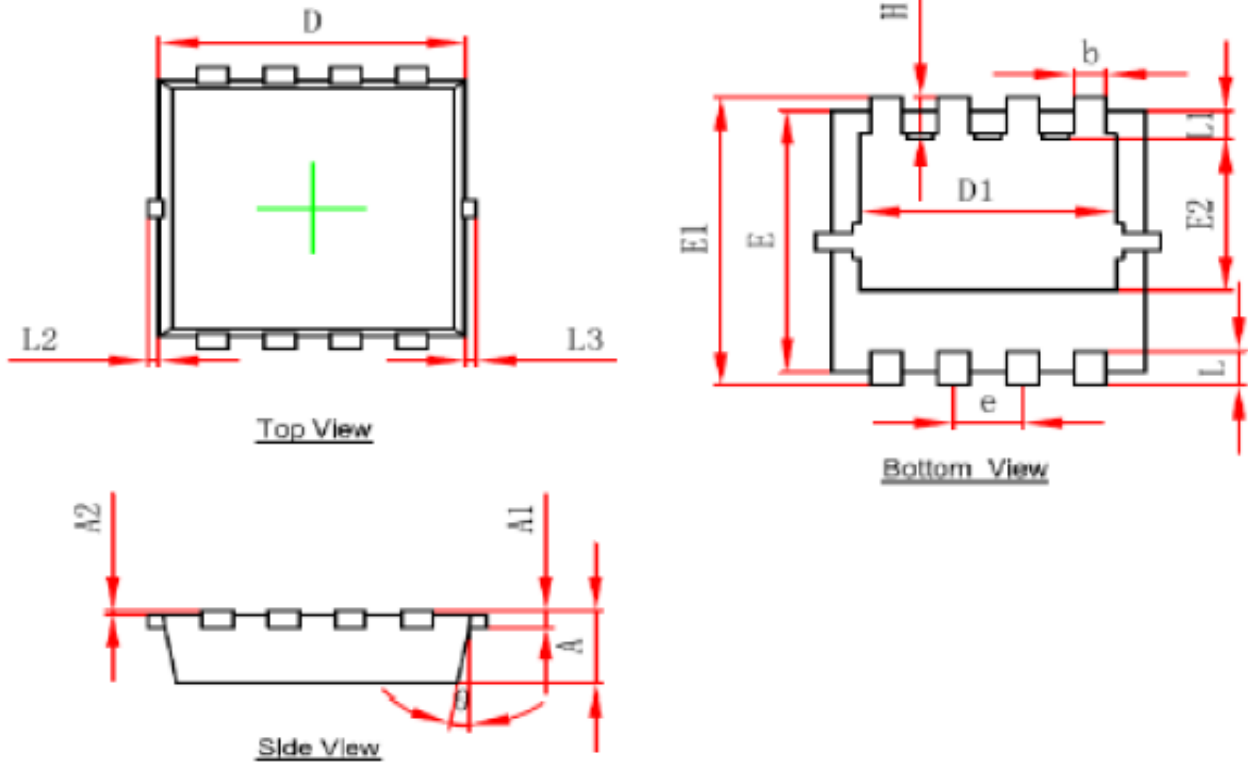


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## N-Channel Enhancement Mode Power MOSFET

### Packing Information

PDFN3\*3-8L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033
A1	0.152 REF		0.008 REF	
A2	0-0.05		0-0.002	
D	2.900	3.100	0.114	0.122
D1	2.300	2.600	0.091	0.102
E	2.900	3.100	0.114	0.122
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.078
b	0.200	0.400	0.008	0.018
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0~0.100		0~0.004	
L3	0~0.100		0~0.004	
H	0.315	0.515	0.012	0.020
$\theta$	9°	13°	9°	13°

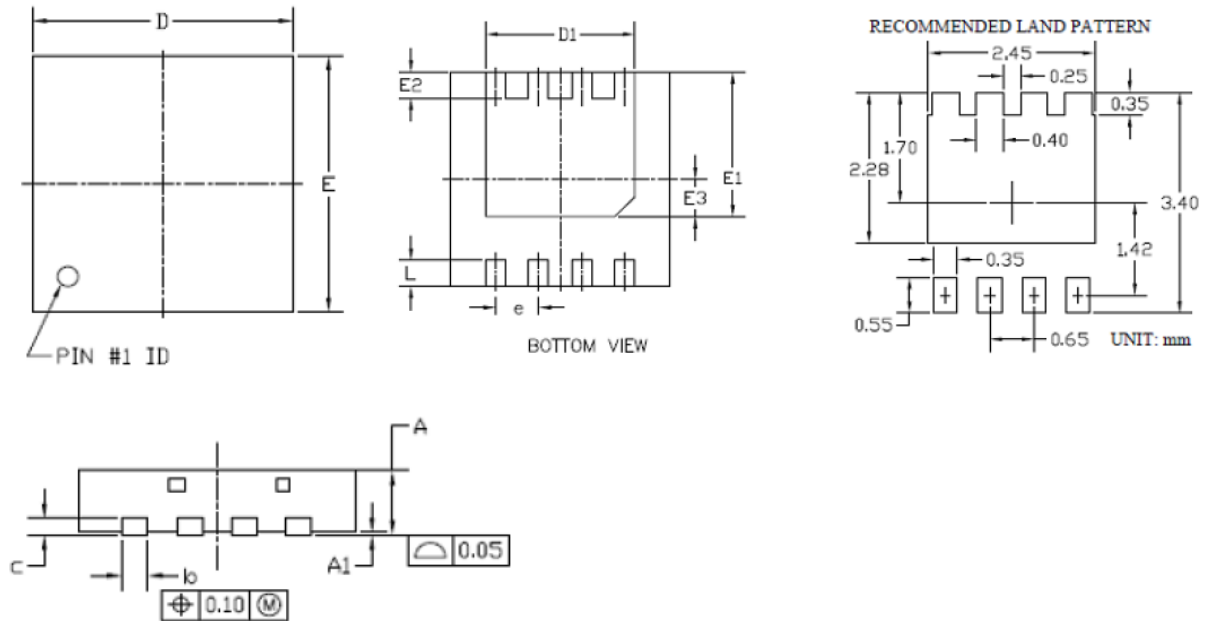


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## N-Channel Enhancement Mode Power MOSFET

### Packing Information

DFN3\*3-8L



Symbol	Dimensions In Millimeters			Dimensions In Inches		
	Min.	NOM	Max.	Min.	NOM	Max.
A	0.70	0.75	0.80	0.028	0.030	0.031
A1			0.05			0.002
b	0.24	0.30	0.35	0.009	0.012	0.014
c	0.10	0.15	0.25	0.004	0.006	0.010
D	3.20	3.30	3.40	0.126	0.130	0.134
D1	2.15	2.25	2.35	0.085	0.089	0.093
E	3.20	3.30	3.40	0.126	0.130	0.134
E1	2.13	2.23	2.33	0.084	0.088	0.092
E2	0.30	0.40	0.50	0.012	0.016	0.020
E3	0.48	0.58	0.68	0.019	0.023	0.027
e	0.65BSC			0.026BSC		
L	0.30	0.40	0.50	0.012	0.016	0.020



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### Notes

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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